74AVCH4T245-Q100

4-bit dual supply translating transceiver with configurable voltage translation; 3-state

Rev. 4 — 11 April 2024

Product data sheet

1. General description

The 74AVCH4T245-Q100 is a 4-bit, dual supply transceiver that enables bidirectional level translation. The device can be used as two 2-bit transceivers or as a 4-bit transceiver. It features two 2-bit input-output ports (nAn and nBn), a direction control input (nDIR), an output enable input (n \overline{OE}) and dual supply pins (V_{CC(A)} and V_{CC(B)}). Both V_{CC(A)} and V_{CC(B)} can be supplied with any voltage between 0.8 V and 3.6 V. This feature makes the device suitable for translating between any of the low voltage nodes (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V and 3.3 V). Pins nAn, n \overline{OE} and nDIR are referenced to V_{CC(A)} and pins nBn are referenced to V_{CC(B)}. A HIGH on nDIR allows transmission from nAn to nBn and a LOW on nDIR allows transmission from nBn to nAn. The output enable input (n \overline{OE}) can be used to disable the outputs so the buses are effectively isolated.

The device is fully specified for partial power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing any damaging backflow current through the device when it is powered down. In suspend mode when either $V_{CC(A)}$ or $V_{CC(B)}$ are at GND level, both nAn and nBn outputs are in the high-impedance OFF-state. The bus hold circuitry on the powered-up side always stays active.

The 74AVCH4T245-Q100 has active bus hold circuitry which is provided to hold unused or floating data inputs at a valid logic level. This feature eliminates the need for external pull-up or pull-down resistors.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Specified from -40 °C to +85 °C and from -40 °C to +125 °C
- · Wide supply voltage range:
 - V_{CC(A)}: 0.8 V to 3.6 V
 - V_{CC(B)}: 0.8 V to 3.6 V
- · Complies with JEDEC standards:
 - JESD8-12 (0.8 V to 1.3 V)
 - JESD8-11 (0.9 V to 1.65 V)
 - JESD8-7 (1.2 V to 1.95 V)
 - JESD8-5 (1.8 V to 2.7 V)
 - JESD8-B (2.7 V to 3.6 V)
- Maximum data rates:
 - 380 Mbit/s (≥ 1.8 V to 3.3 V translation)
 - 200 Mbit/s (≥ 1.1 V to 3.3 V translation)
 - 200 Mbit/s (≥ 1.1 V to 2.5 V translation)
 - 200 Mbit/s (≥ 1.1 V to 1.8 V translation)
 150 Mbit/s (≥ 1.1 V to 1.5 V translation)
 - 100 Mbit/s (≥ 1.1 V to 1.2 V translation)
- Suspend mode
- Bus hold on data inputs
- Latch-up performance exceeds 100 mA per JESD 78 Class II
- Inputs accept voltages up to 3.6 V



- I_{OFF} circuitry provides partial Power-down mode operation
- · ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 3B exceeds 8000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- DHVQFN package with Side-Wettable Flanks enabling Automatic Optical Inspection (AOI) of solder joints

3. Ordering information

Table 1. Ordering information

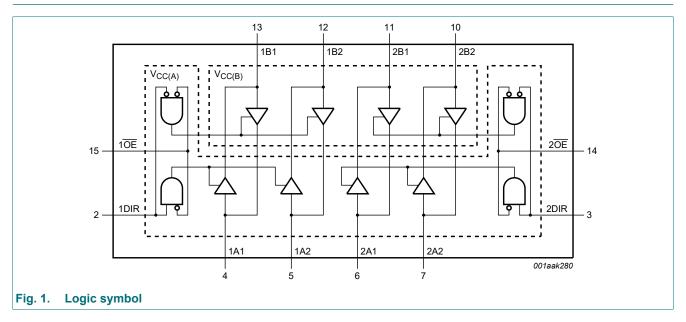
Type number	Package	Package							
	Temperature range	Name	Description	Version					
74AVCH4T245D-Q100	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1					
74AVCH4T245PW-Q100	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1					
74AVCH4T245BQ-Q100	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1					

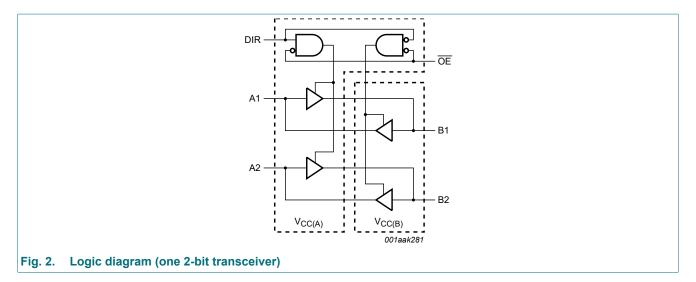
4. Marking

Table 2. Marking codes

Type number	Marking code						
74AVCH4T245D-Q100	74AVCH4T245D						
74AVCH4T245PW-Q100	CH4T245						
74AVCH4T245BQ-Q100	H4T245						

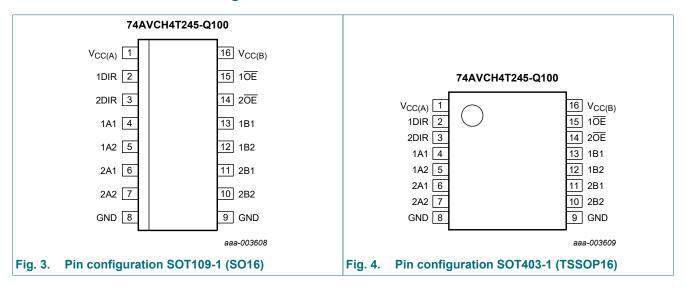
5. Functional diagram



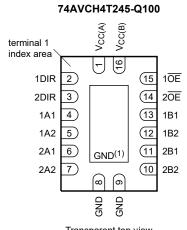


6. Pinning information

6.1. Pinning



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Transparent top view aaa-003610

(1) This is not a ground pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to GND.

Pin configuration SOT763-1 (DHVQFN16) Fig. 5.

6.2. Pin description

Table 3. Pin description

Table 5. I III desci	iiptioii	
Symbol	Pin	Description
V _{CC(A)}	1	supply voltage A (nAn, nOE and nDIR inputs arereferenced to V _{CC(A)})
1DIR, 2DIR	2, 3	direction control
1A1, 1A2	4, 5	data input or output
2A1, 2A2	6, 7	data input or output
GND [1]	8, 9	ground (0 V)
2B2, 2B1	10, 11	data input or output
1B2, 1B1	12, 13	data input or output
20E, 10E	14, 15	output enable input (active LOW)
V _{CC(B)}	16	supply voltage B (nBn inputs are referenced to V _{CC(B)})

All GND pins must be connected to ground (0 V).

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Supply voltage	Input		Input/output [1]	Input/output [1]			
V _{CC(A)} , V _{CC(B)}	nOE [2]	nOE [2] nDIR [2] nA		nBn [2]			
0.8 V to 3.6 V	L	L	nAn = nBn	input			
0.8 V to 3.6 V	L	Н	input	nBn = nAn			
0.8 V to 3.6 V	Н	X	Z	Z			
GND [1]	Х	X	Z	Z			

- If at least one of $V_{CC(A)}$ or $V_{CC(B)}$ is at GND level, the device goes into suspend mode. The nAn, nDIR and nOE input circuit is referenced to $V_{CC(A)}$; The nBn input circuit is referenced to $V_{CC(B)}$.

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC(A)}$	supply voltage A		-0.5	+4.6	V
V _{CC(B)}	supply voltage B		-0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	-50	-	mA
VI	input voltage	[1]	-0.5	+4.6	V
I _{OK}	output clamping current	V _O < 0 V	-50	-	mA
Vo	output voltage	Active mode [1] [2] [3]	-0.5	V _{CCO} + 0.5	V
		Suspend or 3-state mode [1]	-0.5	+4.6	V
I _O	output current	$V_O = 0 V \text{ to } V_{CCO}$ [2]	-	±50	mA
I _{CC}	supply current	per V _{CC(A)} or V _{CC(B)} pin	-	100	mA
I_{GND}	ground current	per GND pin	-100	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	$T_{amb} = -40 ^{\circ}\text{C} \text{ to } +125 ^{\circ}\text{C}$ [4]	-	500	mW

^[1] The minimum input voltage ratings and output voltage ratings may be exceeded if the input and output current ratings are observed.

For SOT403-1 (TSSOP16) package: Ptot derates linearly with 8.5 mW/K above 91 °C.

For SOT763-1 (DHVQFN16) package: Ptot derates linearly with 11.2 mW/K above 106 °C.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Symbol	Parameter	Conditions		Min	Max	Unit
V _{CC(A)}	supply voltage A			8.0	3.6	V
V _{CC(B)}	supply voltage B			0.8	3.6	V
VI	input voltage			0	3.6	V
Vo	output voltage	Active mode	[1]	0	V _{cco}	V
		Suspend or 3-state mode		0	3.6	V
T _{amb}	ambient temperature			-40	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CCI} = 0.8 V to 3.6 V	[2]	-	5	ns/V

^[1] V_{CCO} is the supply voltage associated with the output port.

^[2] V_{CCO} is the supply voltage associated with the output port.

^[3] V_{CCO} + 0.5 V should not exceed 4.6 V.

^[4] For SOT109-1 (SO16) package: P_{tot} derates linearly with 12.4 mW/K above 110 °C.

^[2] V_{CCI} is the supply voltage associated with the input port.

10. Static characteristics

Table 7. Typical static characteristics at T_{amb} = 25 °C

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

V_{CCO} is the supply voltage associated with the output port; V_{CCI} is the supply voltage associated with the data input port.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{OH}	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}; I_O = -1.5 \text{ mA}; V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V}$		-	0.69	-	V
V _{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $I_O = 1.5$ mA; $V_{CC(A)} = V_{CC(B)} = 0.8$ V		-	0.07	-	V
I _I	input leakage current	nDIR, n \overline{OE} input; V _I = 0 V or 3.6 V; V _{CC(A)} = V _{CC(B)} = 0.8 V to 3.6 V		-	±0.025	±0.25	μΑ
I _{BHL}	bus hold LOW current	A or B port; $V_I = 0.42 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$	1]	-	26	-	μΑ
I _{BHH}	bus hold HIGH current	A or B port; $V_I = 0.78 \text{ V}$; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$	2]	-	-24	-	μA
I _{BHLO}	bus hold LOW overdrive current	A or B port; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$	3]	-	27	-	μΑ
I _{BHHO}	bus hold HIGH overdrive current	A or B port; $V_{CC(A)} = V_{CC(B)} = 1.2 \text{ V}$	4]	-	-26	-	μΑ
l _{OZ}	OFF-state output current	A or B port; $V_O = 0 \text{ V or } V_{CCO}$; [$V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	5]	-	±0.5	±2.5	μΑ
		suspend mode A port; $V_O = 0 \text{ V or } V_{CCO}$; [$V_{CC(A)} = 3.6 \text{ V}$; $V_{CC(B)} = 0 \text{ V}$	5]	-	±0.5	±2.5	μΑ
		suspend mode B port; $V_O = 0 \text{ V or } V_{CCO}$; [$V_{CC(A)} = 0 \text{ V}$; $V_{CC(B)} = 3.6 \text{ V}$	5]	-	±0.5	±2.5	μΑ
l _{OFF}	power-off leakage current	A port; V_1 or V_0 = 0 V to 3.6 V; $V_{CC(A)}$ = 0 V; $V_{CC(B)}$ = 0.8 V to 3.6 V		-	±0.1	±1	μΑ
		B port; V_1 or V_0 = 0 V to 3.6 V; $V_{CC(B)}$ = 0 V; $V_{CC(A)}$ = 0.8 V to 3.6 V		-	±0.1	±1	μΑ
C _I	input capacitance	nDIR, n \overline{OE} input; V _I = 0 V or 3.3 V; V _{CC(A)} = V _{CC(B)} = 3.3 V		-	1.0	-	pF
C _{I/O}	input/output capacitance	A and B port; $V_O = 3.3 \text{ V or } 0 \text{ V};$ $V_{CC(A)} = V_{CC(B)} = 3.3 \text{ V}$		-	4.0	-	pF

^[1] The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_I to GND and then raising it to V_{IL} max.

^[2] The bus hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{I} to V_{CC} and then lowering it to V_{IH} min.

^[3] An external driver must source at least I_{BHLO} to switch this node from LOW to HIGH.

^[4] An external driver must sink at least I_{BHHO} to switch this node from HIGH to LOW.

^[5] For I/O ports, the parameter I_{OZ} includes the input leakage current.

Table 8. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

V_{CCO} is the supply voltage associated with the output port; V_{CCI} is the supply voltage associated with the data input port.

Symbol	Parameter	Conditions	-40 °C to	o +85 °C	-40 °C to	Unit	
			Min	Max	Min	Max	
V _{IH}	HIGH-level	data input					
	input voltage	V _{CCI} = 0.8 V	0.70V _{CCI}	-	0.70V _{CCI}	-	٧
		V _{CCI} = 1.1 V to 1.95 V	0.65V _{CCI}	-	0.65V _{CCI}	-	٧
		V _{CCI} = 2.3 V to 2.7 V	1.6	-	1.6	-	٧
		V _{CCI} = 3.0 V to 3.6 V	2	-	2	-	٧
		nDIR, n OE input					
		V _{CC(A)} = 0.8 V	0.70V _{CC(A)}	-	0.70V _{CC(A)}	-	٧
		V _{CC(A)} = 1.1 V to 1.95 V	0.65V _{CC(A)}	-	0.65V _{CC(A)}	-	٧
	V _{CC(A)} = 2.3 V to 2.7 V	1.6	-	1.6	-	٧	
		V _{CC(A)} = 3.0 V to 3.6 V	2	-	2	-	٧
V _{IL}	LOW-level input	data input					
	voltage	V _{CCI} = 0.8 V	-	0.30V _{CCI}	-	0.30V _{CCI}	٧
		V _{CCI} = 1.1 V to 1.95 V	-	0.35V _{CCI}	-	0.35V _{CCI}	٧
		V _{CCI} = 2.3 V to 2.7 V	-	0.7	-	0.7	٧
		V _{CCI} = 3.0 V to 3.6 V	-	0.8	-	0.8	٧
		nDIR, nOE input					
		V _{CC(A)} = 0.8 V	-	0.30V _{CC(A)}	-	0.30V _{CC(A)}	٧
		V _{CC(A)} = 1.1 V to 1.95 V	-	0.35V _{CC(A)}	-	0.35V _{CC(A)}	٧
		V _{CC(A)} = 2.3 V to 2.7 V	-	0.7	-	0.7	٧
		V _{CC(A)} = 3.0 V to 3.6 V	-	0.8	-	0.8	٧
V _{OH}	HIGH-level	$V_I = V_{IH}$ or V_{IL}					
	output voltage	I_{O} = -100 µA; $V_{CC(A)}$ = $V_{CC(B)}$ = 0.8 V to 3.6 V	V _{CCO} - 0.1	-	V _{CCO} - 0.1	-	V
		I_{O} = -3 mA; $V_{CC(A)} = V_{CC(B)} = 1.1 V$	0.85	-	0.85	-	٧
		I_{O} = -6 mA; $V_{CC(A)}$ = $V_{CC(B)}$ = 1.4 V	1.05	-	1.05	-	٧
		I_{O} = -8 mA; $V_{CC(A)} = V_{CC(B)} = 1.65 V$	1.2	-	1.2	-	٧
		I_{O} = -9 mA; $V_{CC(A)} = V_{CC(B)} = 2.3 V$	1.75	-	1.75	-	٧
		I_{O} = -12 mA; $V_{CC(A)} = V_{CC(B)} = 3.0 V$	2.3	-	2.3	-	V
V _{OL}	LOW-level	$V_I = V_{IH}$ or V_{IL}					
	output voltage	$I_O = 100 \mu A;$ $V_{CC(A)} = V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	0.1	-	0.1	V
		I _O = 3 mA; V _{CC(A)} = V _{CC(B)} = 1.1 V	-	0.25	-	0.25	٧
		I _O = 6 mA; V _{CC(A)} = V _{CC(B)} = 1.4 V	-	0.35	-	0.35	V
		I _O = 8 mA; V _{CC(A)} = V _{CC(B)} = 1.65 V	-	0.45	-	0.45	٧
		$I_O = 9 \text{ mA}; V_{CC(A)} = V_{CC(B)} = 2.3 \text{ V}$	-	0.55	-	0.55	٧
		I _O = 12 mA; V _{CC(A)} = V _{CC(B)} = 3.0 V	-	0.7	-	0.7	V
l _l	input leakage current	nDIR, n \overline{OE} input; V _I = 0 V or 3.6 V; V _{CC(A)} = V _{CC(B)} = 0.8 V to 3.6 V	-	±1	-	±5	μΑ

Symbol	Parameter	Conditions	-40 °C t	-40 °C to +85 °C		-40 °C to +125 °C	
			Min	Max	Min	Max	
I _{BHL}	bus hold LOW	A or B port [1]					
	current	V _I = 0.49 V; V _{CC(A)} = V _{CC(B)} = 1.4 V	15	-	15	-	μA
		V _I = 0.58 V; V _{CC(A)} = V _{CC(B)} = 1.65 V	25	-	25	-	μA
		V _I = 0.70 V; V _{CC(A)} = V _{CC(B)} = 2.3 V	45	-	45	-	μA
		V _I = 0.80 V; V _{CC(A)} = V _{CC(B)} = 3.0 V	100	-	90	-	μA
BHH bus hold HIGH	bus hold HIGH	A or B port [2]					
	current	V _I = 0.91 V; V _{CC(A)} = V _{CC(B)} = 1.4 V	-15	-	-15	-	μA
		V _I = 1.07 V; V _{CC(A)} = V _{CC(B)} = 1.65 V	-25	-	-25	-	μA
		V _I = 1.60 V; V _{CC(A)} = V _{CC(B)} = 2.3 V	-45	-	-45	-	μA
		V _I = 2.00 V; V _{CC(A)} = V _{CC(B)} = 3.0 V	-100	-	-100	-	μA
I _{BHLO}	bus hold LOW	A or B port [3]					
	overdrive current	V _{CC(A)} = V _{CC(B)} = 1.6 V	125	-	125	-	μA
		V _{CC(A)} = V _{CC(B)} = 1.95 V	200	-	200	-	μA
		$V_{CC(A)} = V_{CC(B)} = 2.7 \text{ V}$	300	-	300	-	μA
		$V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	500	-	500	-	μA
I _{BHHO}	bus hold HIGH	A or B port [4]					
	overdrive current	$V_{CC(A)} = V_{CC(B)} = 1.6 \text{ V}$	-125	-	-125	-	μA
	Carrent	V _{CC(A)} = V _{CC(B)} = 1.95 V	-200	-	-200	-	μA
		$V_{CC(A)} = V_{CC(B)} = 2.7 \text{ V}$	-300	-	-300	-	μA
		$V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	-500	-	-500	-	μA
l _{OZ}	OFF-state output current	A or B port; $V_O = 0 \text{ V or } V_{CCO}$; [5] $V_{CC(A)} = V_{CC(B)} = 3.6 \text{ V}$	-	±5	-	±30	μA
		suspend mode A port; $V_O = 0 \text{ V or } V_{CCO}; V_{CC(A)} = 3.6 \text{ V};$ $V_{CC(B)} = 0 \text{ V}$	-	±5	-	±30	μΑ
		suspend mode B port; [5] $V_O = 0 \text{ V or } V_{CCO}; V_{CC(A)} = 0 \text{ V};$ $V_{CC(B)} = 3.6 \text{ V}$	-	±5	-	±30	μΑ
I _{OFF}	power-off leakage current	A port; V_1 or $V_0 = 0$ V to 3.6 V; $V_{CC(A)} = 0$ V; $V_{CC(B)} = 0.8$ V to 3.6 V	-	±5	-	±30	μA
		B port; V_I or $V_O = 0$ V to 3.6 V; $V_{CC(B)} = 0$ V; $V_{CC(A)} = 0.8$ V to 3.6 V	-	±5	-	±30	μA

Symbol	Parameter	Conditions	-40 °C t	o +85 °C	-40 °C to	Unit	
			Min	Max	Min	Max	
Icc	supply current	A port; $V_I = 0 \text{ V or } V_{CCI}$; $I_O = 0 \text{ A}$					
		$V_{CC(A)} = 0.8 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	10	-	55	μA
		V _{CC(A)} = 1.1 V to 3.6 V; V _{CC(B)} = 1.1 V to 3.6 V	-	8	-	50	μΑ
		V _{CC(A)} = 3.6 V; V _{CC(B)} = 0 V	-	8	-	50	μA
		V _{CC(A)} = 0 V; V _{CC(B)} = 3.6 V	-2	-	-12	-	μA
		B port; $V_I = 0 \text{ V or } V_{CCI}$; $I_O = 0 \text{ A}$					
		$V_{CC(A)} = 0.8 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 0.8 \text{ V to } 3.6 \text{ V}$	-	10	-	55	μA
		V _{CC(A)} = 1.1 V to 3.6 V; V _{CC(B)} = 1.1 V to 3.6 V	-	8	-	50	μA
		V _{CC(A)} = 3.6 V; V _{CC(B)} = 0 V	-2	-	-12	-	μA
		V _{CC(A)} = 0 V; V _{CC(B)} = 3.6 V	-	8	-	50	μA
		A plus B port ($I_{CC(A)} + I_{CC(B)}$); $I_O = 0$ A; $V_I = 0$ V or V_{CCI} ; $V_{CC(A)} = 0.8$ V to 3.6 V; $V_{CC(B)} = 0.8$ V to 3.6 V	-	20	-	70	μА
		A plus B port ($I_{CC(A)} + I_{CC(B)}$); $I_O = 0$ A; $V_I = 0$ V or V_{CCI} ; $V_{CC(A)} = 1.1$ V to 3.6 V; $V_{CC(B)} = 1.1$ V to 3.6 V	-	16	-	65	μΑ

^[1] The bus hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_I to GND and then raising it to V_{IL} max.

[5] For I/O ports, the parameter I_{OZ} includes the input leakage current.

Table 9. Typical total supply current $(I_{CC(A)} + I_{CC(B)})$

V _{CC(A)}	$V_{CC(B)}$							
	0 V	0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
0 V	0	0.1	0.1	0.1	0.1	0.1	0.1	μΑ
0.8 V	0.1	0.1	0.1	0.1	0.1	0.3	1.6	μA
1.2 V	0.1	0.1	0.1	0.1	0.1	0.1	0.8	μΑ
1.5 V	0.1	0.1	0.1	0.1	0.1	0.1	0.4	μA
1.8 V	0.1	0.1	0.1	0.1	0.1	0.1	0.2	μA
2.5 V	0.1	0.3	0.1	0.1	0.1	0.1	0.1	μA
3.3 V	0.1	1.6	0.8	0.4	0.2	0.1	0.1	μΑ

^[2] The bus hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_I to V_{CC} and then lowering it to V_{IH} min.

^[3] An external driver must source at least I_{BHLO} to switch this node from LOW to HIGH.

^[4] An external driver must sink at least I_{BHHO} to switch this node from HIGH to LOW.

11. Dynamic characteristics

Table 10. Typical power dissipation capacitance at $V_{CC(A)} = V_{CC(B)}$ and $T_{amb} = 25 \,^{\circ}C$ [1] [2]

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions			V _{CC(A)} =	= V _{CC(B)}			Unit
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
C _{PD}	power dissipation capacitance	A port: (direction nAn to nBn); output enabled	0.2	0.2	0.2	0.2	0.3	0.4	pF
		A port: (direction nAn to nBn); output disabled	0.2	0.2	0.2	0.2	0.3	0.4	pF
		A port: (direction nBn to nAn); output enabled	9.5	9.7	9.8	9.9	10.7	11.9	pF
		A port: (direction nBn to nAn); output disabled	0.6	0.6	0.6	0.6	0.7	0.7	pF
		B port: (direction nAn to nBn); output enabled	9.5	9.7	9.8	9.9	10.7	11.9	pF
		B port: (direction nAn to nBn); output disabled	0.6	0.6	0.6	0.6	0.7	0.7	pF
		B port: (direction nBn to nAn); output enabled	0.2	0.2	0.2	0.2	0.3	0.4	pF
		B port: (direction nBn to nAn); output disabled	0.2	0.2	0.2	0.2	0.3	0.4	pF

[1] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = load capacitance in pF;

V_{CC} = supply voltage in V;

N = number of inputs switching;

$$\begin{split} &\Sigma(C_L \times V_{CC}^{-2} \times f_o) = \text{sum of the outputs.} \\ [2] \quad &f_i = 10 \text{ MHz; } V_i = \text{GND to } V_{CC}; \, t_r = t_f = 1 \text{ ns; } C_L = 0 \text{ pF; } R_L = \infty \Omega. \end{split}$$

Table 11. Typical dynamic characteristics at $V_{CC(A)}$ = 0.8 V and T_{amb} = 25 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 8; for wave forms see Fig. 6 and Fig. 7. t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

Symbol	Parameter	Conditions	V _{CC(B)}							
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	1	
t _{pd} propagation dela	propagation delay	nAn to nBn	14.5	7.3	6.5	6.2	5.9	6.0	ns	
		nBn to nAn	14.5	12.7	12.4	12.3	12.1	12.0	ns	
t _{dis}	disable time	nOE to nAn	14.3	14.3	14.3	14.3	14.3	14.3	ns	
			n OE to nBn	17.0	9.9	9.0	9.4	9.0	9.7	ns
t _{en}	enable time	n OE to nAn	18.2	18.2	18.2	18.2	18.2	18.2	ns	
		n OE to nBn	19.2	10.7	9.8	9.6	9.7	10.2	ns	

Table 12. Typical dynamic characteristics at $V_{CC(B)}$ = 0.8 V and T_{amb} = 25 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 8; for wave forms see Fig. 6 and Fig. 7 t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

Symbol	Parameter	Conditions	V _{CC(A)}						
			0.8 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
t _{pd} propa	propagation delay	nAn to nBn	14.5	12.7	12.4	12.3	12.1	12.0	ns
		nBn to nAn	14.5	7.3	6.5	6.2	5.9	6.0	ns
t _{dis}	disable time	n OE to nAn	14.3	5.5	4.1	4.0	3.0	3.5	ns
		nOE to nBn	17.0	13.8	13.4	13.1	12.9	12.7	ns
t _{en}	enable time	n OE to nAn	18.2	5.6	4.0	3.2	2.4	2.2	ns
		n OE to nBn	19.2	14.6	14.1	13.9	13.7	13.6	ns

Table 13. Dynamic characteristics for temperature range -40 °C to +85 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 8; for wave forms see Fig. 6 and Fig. 7. t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

Symbol	Parameter	Conditions	V _{CC(B)}									Unit	
			1.2 V	± 0.1 V	1.5 V ± 0.1 V		1.8 V ±	0.15 V	2.5 V	± 0.2 V	3.3 V	± 0.3 V	1
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.1 V to 1.3 V												
t _{pd} propagation	nAn to nBn	0.5	9.4	0.5	7.1	0.5	6.2	0.5	5.2	0.5	5.1	ns	
	delay	nBn to nAn	0.5	9.4	0.5	8.9	0.5	8.7	0.5	8.4	0.5	8.2	ns
t _{dis}	disable time	nOE to nAn	1.8	10.9	1.8	10.9	1.8	10.9	1.8	10.9	1.8	10.9	ns
		n OE to nBn	1.9	12.4	1.9	9.6	1.9	9.5	1.4	8.1	1.2	9.1	ns
t _{en}	enable time	nOE to nAn	1.4	12.8	1.4	12.8	1.4	12.8	1.4	12.8	1.4	12.8	ns
		nOE to nBn	1.1	13.3	1.1	10.0	1.1	8.9	1.0	7.9	1.0	7.7	ns
V _{CC(A)} =	1.4 V to 1.6 V												
t _{pd}	propagation	nAn to nBn	0.3	8.9	0.3	6.3	0.3	5.2	0.3	4.2	0.3	4.2	ns
	delay	nBn to nAn	0.7	7.1	0.7	6.3	0.5	6.0	0.4	5.7	0.3	5.6	ns
t _{dis}	disable time	nOE to nAn	1.8	10.2	1.8	10.2	1.5	10.2	1.3	10.2	1.6	10.2	ns
		nOE to nBn	1.9	11.3	1.9	10.3	1.9	9.1	1.4	7.4	1.2	7.6	ns
t _{en}	enable time	nOE to nAn	1.1	9.4	1.4	9.4	1.1	9.4	0.7	9.4	0.4	9.4	ns
		nOE to nBn	1.4	12.1	1.4	9.6	1.1	7.7	0.9	5.8	0.9	5.6	ns
V _{CC(A)} =	1.65 V to 1.95	V	•		•								
t _{pd}	propagation	nAn to nBn	0.1	8.7	0.1	6.0	0.1	4.9	0.1	3.9	0.3	3.9	ns
	delay	nBn to nAn	0.6	6.2	0.6	5.3	0.5	4.9	0.3	4.6	0.3	4.5	ns
t _{dis}	disable time	nOE to nAn	1.8	8.6	1.6	8.6	1.8	8.6	1.3	8.6	1.6	8.6	ns
		nOE to nBn	1.7	10.9	1.7	9.9	1.6	8.7	1.2	6.9	1.0	6.9	ns
t _{en}	enable time	nOE to nAn	1.0	7.2	1.0	7.2	1.0	7.2	0.6	7.2	0.4	7.2	ns
		nOE to nBn	1.2	11.7	1.2	9.2	1.0	7.4	0.8	5.3	0.8	4.6	ns
V _{CC(A)} =	2.3 V to 2.7 V												
t _{pd}	propagation	nAn to nBn	0.1	8.4	0.1	5.7	0.1	4.6	0.2	3.5	0.1	3.6	ns
	delay	nBn to nAn	0.6	5.2	0.6	4.2	0.4	3.9	0.2	3.4	0.2	3.3	ns
t _{dis}	disable time	nOE to nAn	1.0	6.2	1.0	6.2	1.0	6.2	1.0	6.2	1.0	6.2	ns
		n OE to nBn	1.5	10.4	1.5	8.8	1.3	8.2	1.1	6.2	0.9	5.2	ns
t _{en}	enable time	nOE to nAn	0.7	4.8	0.7	4.8	0.7	4.8	0.6	4.8	0.4	4.8	ns
		n OE to nBn	0.9	11.3	0.9	8.8	0.8	7.0	0.6	4.8	0.6	4.0	ns
V _{CC(A)} =	3.0 V to 3.6 V												
t _{pd}	propagation	nAn to nBn	0.1	8.2	0.1	5.6	0.1	4.5	0.1	3.3	0.1	2.9	ns
	delay	nBn to nAn	0.6	5.1	0.6	4.2	0.4	3.4	0.2	3.0	0.1	2.8	ns
t _{dis}	disable time	nOE to nAn	0.7	5.6	0.7	5.6	0.7	5.6	0.7	5.6	0.7	5.6	ns
		nOE to nBn	1.4	10.2	1.4	9.3	1.2	8.1	1.0	6.4	0.8	6.2	ns
t _{en}	enable time	n OE to nAn	0.6	3.8	0.6	3.8	0.6	3.8	0.6	3.8	0.4	3.8	ns
		nOE to nBn	0.8	11.3	0.8	8.7	0.6	6.8	0.5	4.7	0.5	3.8	ns

Table 14. Dynamic characteristics for temperature range -40 °C to +125 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 8; for wave forms see Fig. 6 and Fig. 7 t_{pd} is the same as t_{PLH} and t_{PHL} ; t_{dis} is the same as t_{PLZ} and t_{PHZ} ; t_{en} is the same as t_{PZL} and t_{PZH} .

Symbol	Parameter	ter Conditions	V _{CC(B)}									Unit	
			1.2 V ± 0.1 V		1.5 V ± 0.1 V		1.8 V ± 0.15 V		V 2.5 V ± 0.2 V		3.3 V ± 0.3 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
V _{CC(A)} =	1.1 V to 1.3 V												
t _{pd}	propagation	nAn to nBn	0.5	10.4	0.5	7.9	0.5	6.9	0.5	5.8	0.5	5.7	ns
	delay	nBn to nAn	0.5	10.4	0.5	9.8	0.5	9.6	0.5	9.3	0.5	9.1	ns
t _{dis}	disable time	nOE to nAn	1.8	12.0	1.8	12.0	1.8	12.0	1.8	12.0	1.8	12.0	ns
		nOE to nBn	1.9	13.7	1.9	10.6	1.9	10.5	1.4	9.0	1.2	10.1	ns
t _{en}	enable time	nOE to nAn	1.4	14.1	1.4	14.1	1.4	14.1	1.4	14.1	1.4	14.1	ns
		nOE to nBn	1.1	14.7	1.1	11.0	1.1	9.8	1.0	8.7	1.0	8.5	ns
V _{CC(A)} =	1.4 V to 1.6 V				•		•						
t _{pd}	propagation	nAn to nBn	0.3	9.8	0.3	7.0	0.3	5.8	0.3	4.7	0.3	4.7	ns
	delay	nBn to nAn	0.7	7.9	0.7	7.0	0.5	6.6	0.4	6.3	0.3	6.2	ns
t _{dis}	disable time	nOE to nAn	1.8	11.3	1.8	11.3	1.5	11.3	1.3	11.3	1.6	11.3	ns
		nOE to nBn	1.9	12.5	1.9	11.4	1.9	10.1	1.4	8.2	1.2	8.4	ns
t _{en}	enable time	nOE to nAn	1.1	10.4	1.4	10.4	1.1	10.4	0.7	10.4	0.4	10.4	ns
		nOE to nBn	1.4	13.3	1.4	10.6	1.1	8.5	0.9	6.4	0.9	6.2	ns
V _{CC(A)} =	1.65 V to 1.95	V			'								
t _{pd}	propagation	nAn to nBn	0.1	9.6	0.1	6.6	0.1	5.4	0.1	4.3	0.3	4.3	ns
	delay	nBn to nAn	0.6	6.9	0.6	5.9	0.5	5.4	0.3	5.1	0.3	5.0	ns
t _{dis}	disable time	nOE to nAn	1.8	9.5	1.6	9.5	1.8	9.5	1.3	9.5	1.6	9.5	ns
		nOE to nBn	1.7	12.0	1.7	10.9	1.6	9.6	1.2	7.6	1.0	7.6	ns
t _{en}	enable time	nOE to nAn	1.0	8.0	1.0	8.0	1.0	8.0	0.6	8.0	0.4	8.0	ns
		nOE to nBn	1.2	12.9	1.2	10.2	1.0	8.2	8.0	5.9	0.8	5.1	ns
V _{CC(A)} =	2.3 V to 2.7 V					•							
t _{pd}	propagation	nAn to nBn	0.1	9.3	0.1	6.3	0.1	5.1	0.2	4.0	0.1	4.0	ns
	delay	nBn to nAn	0.6	5.8	0.6	4.7	0.4	4.3	0.2	3.9	0.2	3.8	ns
t _{dis}	disable time	nOE to nAn	1.0	6.9	1.0	6.9	1.0	6.9	1.0	6.9	1.0	6.9	ns
		nOE to nBn	1.5	11.5	1.5	10.4	1.3	9.1	1.1	6.9	0.9	5.8	ns
t _{en}	enable time	n OE to nAn	0.7	5.3	0.7	5.3	0.7	5.3	0.6	5.3	0.4	5.3	ns
		nOE to nBn	0.9	12.4	0.9	9.7	0.8	7.7	0.6	5.3	0.6	4.4	ns
V _{CC(A)} =	3.0 V to 3.6 V			•		'				,		'	
t _{pd}	propagation	nAn to nBn	0.1	9.1	0.1	6.2	0.1	5.0	0.1	3.8	0.1	3.3	ns
	delay	nBn to nAn	0.6	5.7	0.6	4.7	0.4	3.9	0.2	3.4	0.1	3.3	ns
t _{dis}	disable time	n OE to nAn	0.7	6.2	0.7	6.2	0.7	6.2	0.7	6.2	0.7	6.2	ns
		nOE to nBn	1.4	11.3	1.4	10.3	1.2	9.0	1.0	7.1	0.8	6.9	ns
t _{en}	enable time	n OE to nAn	0.6	4.2	0.6	4.2	0.6	4.2	0.6	4.2	0.4	4.2	ns
		nOE to nBn	0.8	12.4	0.8	9.6	0.6	7.5	0.5	5.2	0.5	4.2	ns

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11.1. Waveforms and test circuit

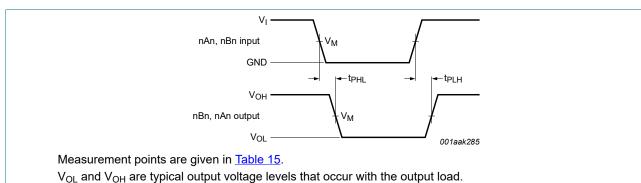


Fig. 6. The data input (nAn, nBn) to output (nBn, nAn) propagation delay times

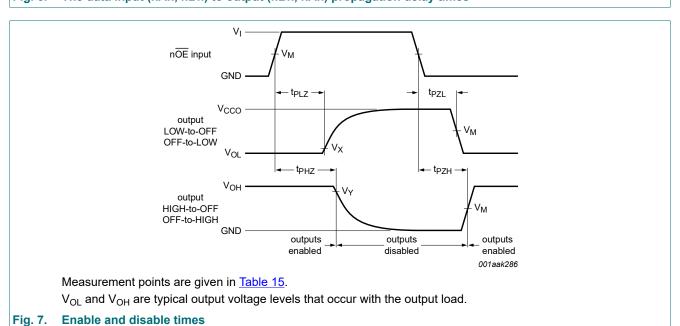
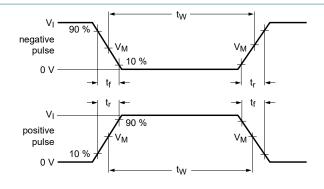
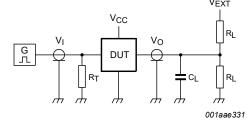


Table 15. Measurement points

Table 101 medeat enter points									
Supply voltage	Input [1]	Output [2]							
V _{CC(A)} , V _{CC(B)}	V _M	V _M	V _X	V _Y					
0.8 V to 1.6 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.1 V	V _{OH} - 0.1 V					
1.65 V to 2.7 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.15 V	V _{OH} - 0.15 V					
3.0 V to 3.6 V	0.5V _{CCI}	0.5V _{CCO}	V _{OL} + 0.3 V	V _{OH} - 0.3 V					

- [1] V_{CCI} is the supply voltage associated with the data input port.
- [2] V_{CCO} is the supply voltage associated with the output port.





Test data is given in Table 16.

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

 R_T = Termination resistance.

V_{EXT} = External voltage for measuring switching times.

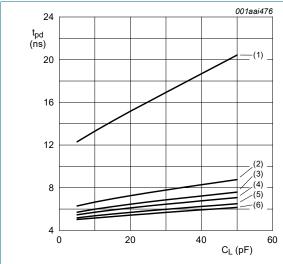
Fig. 8. Test circuit for measuring switching times

Table 16. Test data

Supply voltage Input			Load		V _{EXT}				
V _{CC(A)} , V _{CC(B)}	V _I [1]	Δt/ΔV [2]	CL	R _L	t _{PLH} , t _{PHL}	t _{PZH} , t _{PHZ}	t _{PZL} , t _{PLZ} [3]		
0.8 V to 1.6 V	V _{CCI}	≤ 1.0 ns/V	15 pF	2 kΩ	open	GND	2V _{CCO}		
1.65 V to 2.7 V	V _{CCI}	≤ 1.0 ns/V	15 pF	2 kΩ	open	GND	2V _{CCO}		
3.0 V to 3.6 V	V _{CCI}	≤ 1.0 ns/V	15 pF	2 kΩ	open	GND	2V _{CCO}		

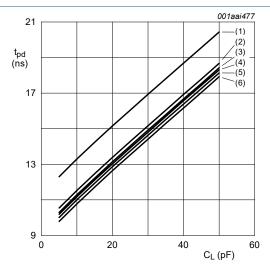
- [1] V_{CCI} is the supply voltage associated with the data input port.
- [2] dV/dt ≥ 1.0 V/ns
- [3] V_{CCO} is the supply voltage associated with the output port.

11.2. Typical propagation delay characteristics



- a. Propagation delay (nAn to nBn); V_{CC(A)} = 0.8 V
 - (1) $V_{CC(B)} = 0.8 \text{ V}.$
 - (2) $V_{CC(B)} = 1.2 \text{ V}.$ (3) $V_{CC(B)} = 1.5 \text{ V}.$

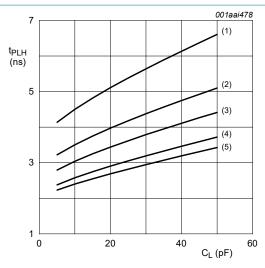
 - (4) $V_{CC(B)} = 1.8 \text{ V}.$
 - (5) $V_{CC(B)} = 2.5 \text{ V}.$
 - (6) $V_{CC(B)} = 3.3 \text{ V}.$



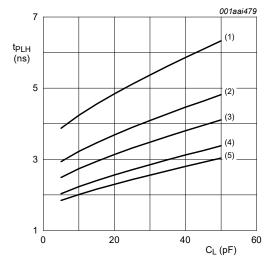
- b. Propagation delay (nAn to nBn); $V_{CC(B)} = 0.8 \text{ V}$
 - (1) $V_{CC(A)} = 0.8 \text{ V}.$
 - (2) $V_{CC(A)} = 1.2 \text{ V}.$
 - (3) $V_{CC(A)} = 1.5 \text{ V}.$

 - (4) $V_{CC(A)} = 1.8 \text{ V}.$ (5) $V_{CC(A)} = 2.5 \text{ V}.$
 - (6) $V_{CC(A)} = 3.3 \text{ V}.$

Typical propagation delay versus load capacitance; T_{amb} = 25 °C Fig. 9.



a. LOW to HIGH propagation delay (nAn to nBn); $V_{CC(A)} = 1.2 \text{ V}$

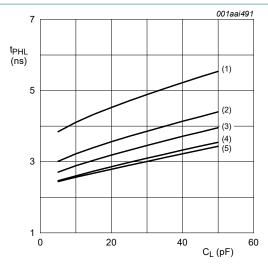


c. LOW to HIGH propagation delay (nAn to nBn); $V_{CC(A)} = 1.5 \text{ V}$

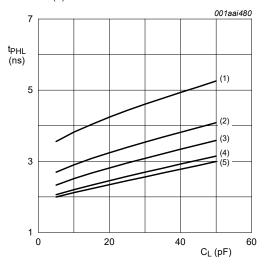
- (1) $V_{CC(B)} = 1.2 \text{ V}.$
- (2) $V_{CC(B)} = 1.5 \text{ V.}$ (3) $V_{CC(B)} = 1.8 \text{ V.}$ (4) $V_{CC(B)} = 2.5 \text{ V.}$

- (5) $V_{CC(B)} = 3.3 \text{ V}.$

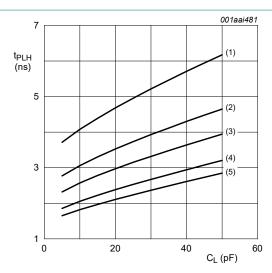
Fig. 10. Typical propagation delay versus load capacitance; T_{amb} = 25 °C



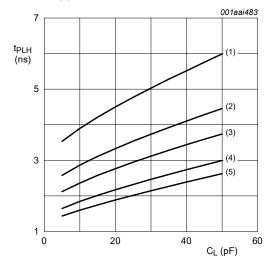
b. HIGH to LOW propagation delay (nAn to nBn); $V_{CC(A)} = 1.2 \text{ V}$



d. HIGH to LOW propagation delay (nAn to nBn); $V_{CC(A)} = 1.5 \text{ V}$



a. LOW to HIGH propagation delay (nAn to nBn); $V_{CC(A)} = 1.8 \text{ V}$

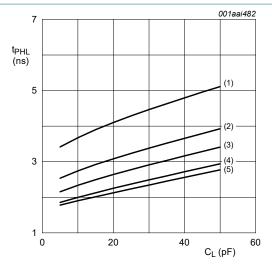


c. LOW to HIGH propagation delay (nAn to nBn); $V_{CC(A)} = 2.5 V$

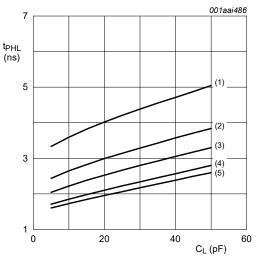
- (1) $V_{CC(B)} = 1.2 \text{ V}.$
- (2) $V_{CC(B)} = 1.5 \text{ V.}$ (3) $V_{CC(B)} = 1.8 \text{ V.}$ (4) $V_{CC(B)} = 2.5 \text{ V.}$

- (5) $V_{CC(B)} = 3.3 \text{ V}.$

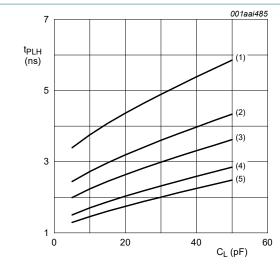
Fig. 11. Typical propagation delay versus load capacitance; T_{amb} = 25 °C

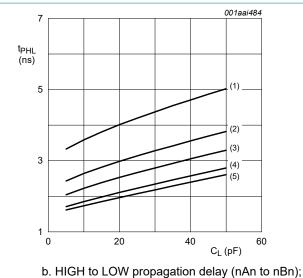


b. HIGH to LOW propagation delay (nAn to nBn); $V_{CC(A)} = 1.8 \text{ V}$



d. HIGH to LOW propagation delay (nAn to nBn); $V_{CC(A)} = 2.5 \text{ V}$





 $V_{CC(A)} = 3.3 \text{ V}$

a. LOW to HIGH propagation delay (nAn to nBn); $V_{CC(A)} = 3.3 \text{ V}$

- (1) $V_{CC(B)} = 1.2 \text{ V}.$
- (2) $V_{CC(B)} = 1.5 \text{ V}.$ (3) $V_{CC(B)} = 1.8 \text{ V}.$
- (4) $V_{CC(B)} = 2.5 \text{ V}.$ (5) $V_{CC(B)} = 3.3 \text{ V}.$

Fig. 12. Typical propagation delay versus load capacitance; T_{amb} = 25 °C

12. Package outline

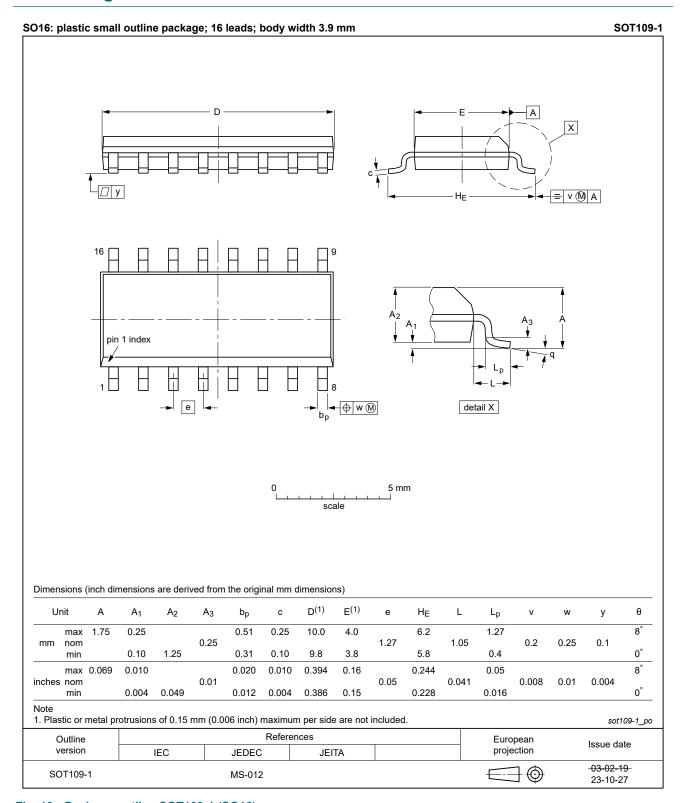


Fig. 13. Package outline SOT109-1 (SO16)

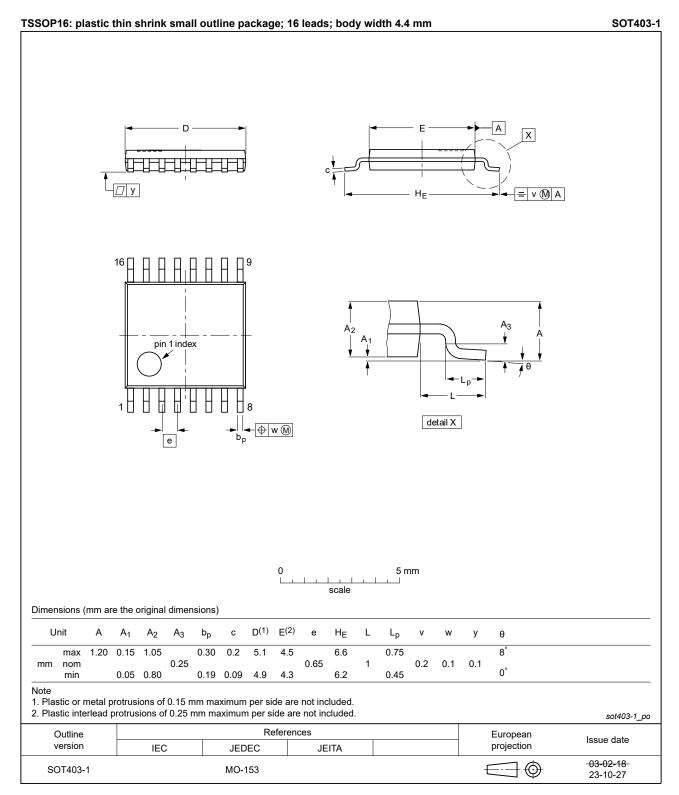


Fig. 14. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm SOT763-1

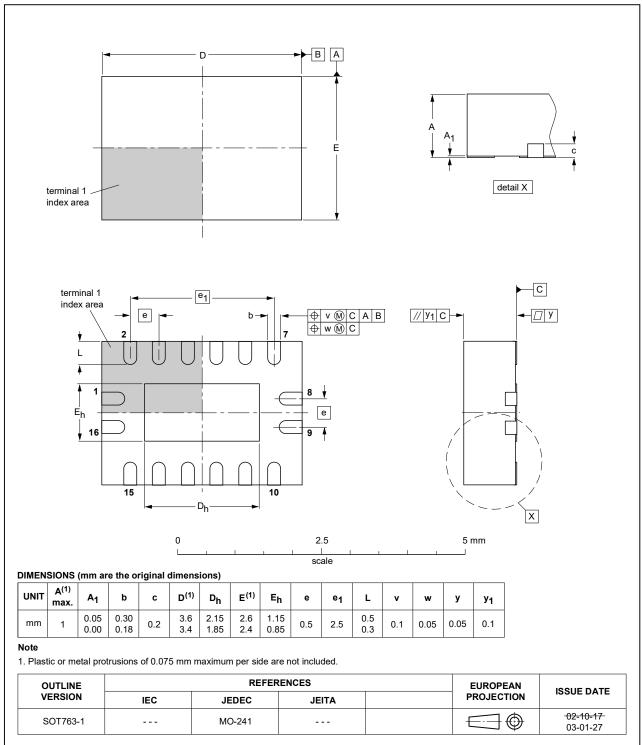


Fig. 15. Package outline SOT763-1 (DHVQFN16)

13. Abbreviations

Table 17. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
НВМ	Human Body Model

14. Revision history

Table 18. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes				
74AVCH4T245_Q100 v.4	20240411	Product data sheet	-	74AVCH4T245_Q100 v.3				
Modifications:	and MO-153	Fig. 13, Fig. 14: Aligned SO and TSSOP package outline drawings to JEDEC MS-0 ^{-/-} and MO-153. Section 2: ESD specification updated according to the latest JEDEC standard.						
74AVCH4T245_Q100 v.3	20200312	Product data sheet	-	74AVCH4T245_Q100 v.2				
Modifications:	guidelines o Legal texts I Section 2 up	nave been adapted to the r	new company nan	ne where appropriate.				
74AVCH4T245_Q100 v.2	20151217	Product data sheet	-	74AVCH4T245_Q100 v.1				
Modifications:	<u>Table 5</u> : conditions I _{CC} and I _{GND} changed (errata).							
74AVCH4T245_Q100 v.1	20130916	Product data sheet	-	-				

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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